

PRIMERGY RX200 S8

System configurator and order-information guide

June 2014

Contents

4x 2.5" Hot-plug HDD or SSD



8x 2.5" Hot-plug HDD or SDD

Instructions Configuration c

Configurator

0 System software

I Basic unit

II ProcessorIII Memory

IV Graphics

V Accessible drives

VI Drive Bay for 4x /8x 2.5" HD Basic Unit

VII Modular Raid 0/1, Raid5 for 4x 2.5" / 8x 2.5" SAS or SATA HD's.

On-board Controller for 4x 2.5" SATA or SAS HD's

VIII 4x or 8x 2.5" SAS / SATA Hard disk drives

IX External SAS Disk Array, SAS backup drives or SCSI peripheral devices

X Fibre-Channel controller

XI Communication/Network

XII System Management Products (RemoteView)

XIII Miscellaneous

XIV Country specific power cord

Change report

PRIMERGY Server

Instructions

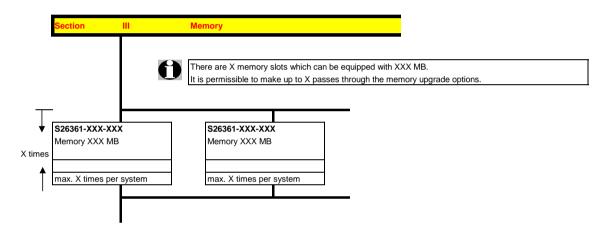
This document contains basic product and configuration information that will enable you to configure your system via PC-/SystemArchitect.

Only these tools will ensure a fast and proper configuration of your PRIMERGY server or your complete PRIMERGY Rack system.

You can configure your individual PRIMERGY server in order to adjust your specific requirements.

The System configurator is divided into several chapters that are identical to the current price list and PC-/SystemArchitect.

Please follow the lines. If there is a junction, you can choose which way or component you would like to take. Go through the configurator by following the lines from the top to the bottom.



In one chapter you can only select as many components (here 4x) as the arrow indicates.



Please note that there are information symbols which indicate necessary information.



For further information see:

http://ts.fujitsu.com/products/standard_servers/index.html

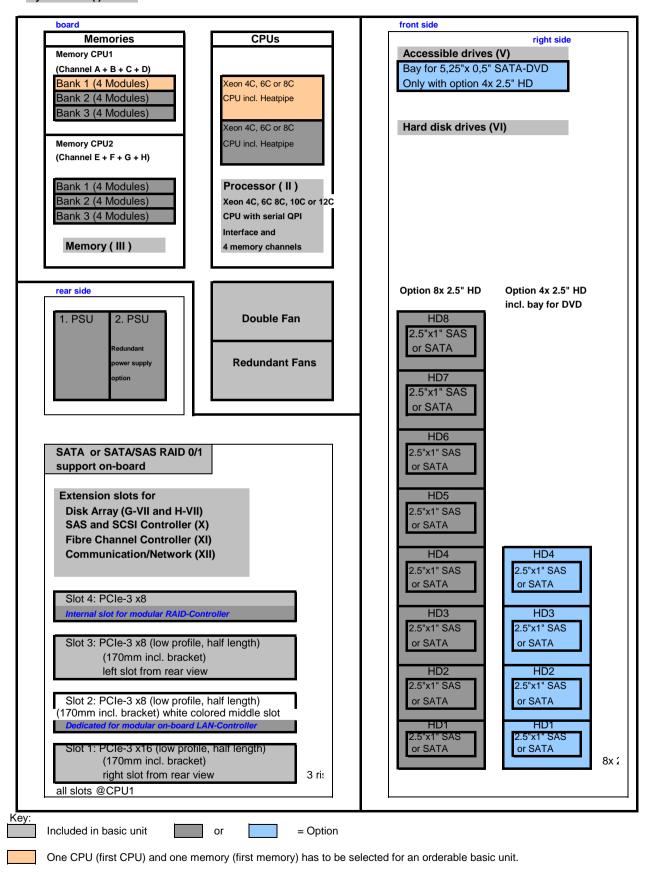
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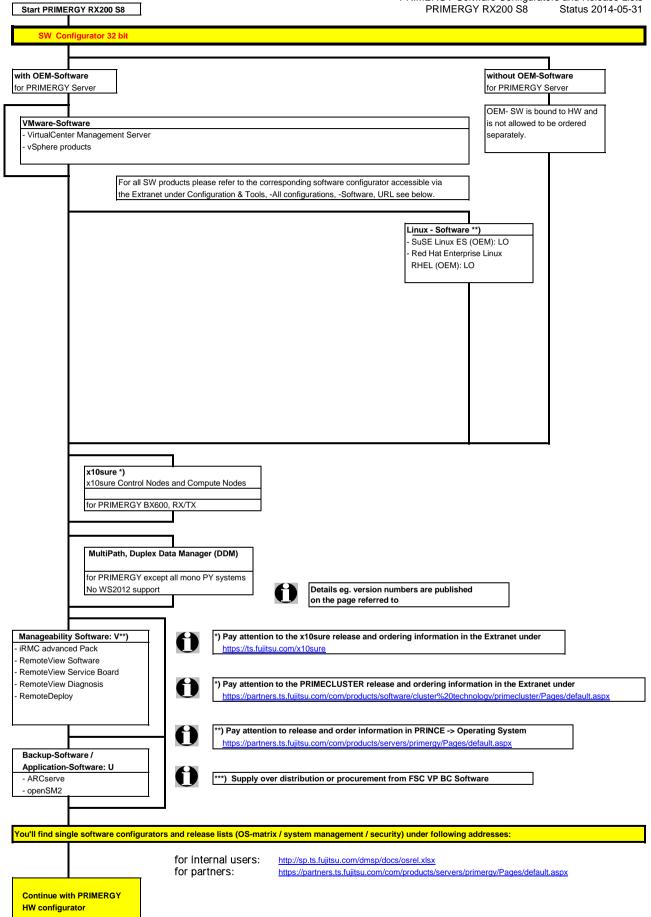
https://partners.ts.fujitsu.com/com/order-supply/configurators/primergy_config/current/Pages/default.aspx (extranet)

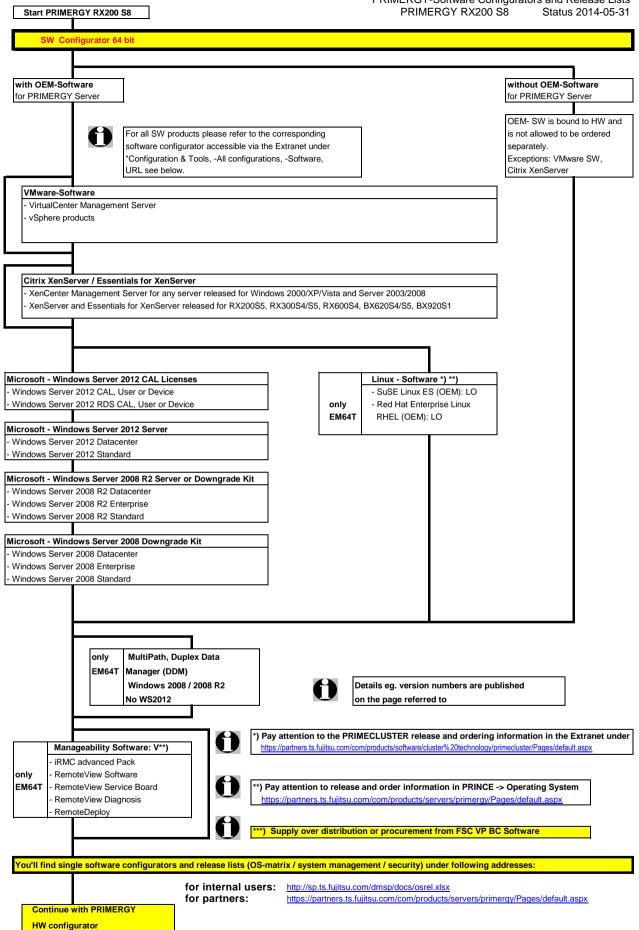
Prices and availability see price list and PC-/SystemArchitect. Subject to change and errors excepted.

Configuration diagram PRIMERGY RX200 S8

System unit (I)







Start PRIMERGY RX200 S8

Section

Basic un



System unit consisting of:

* 1U Housing without power supply modules

(PSU has to be configured min 1x)

- Fans
 - Redundant and hot plug system double-fans 4x for 1 CPU / 6x for 2 CPU configuration (n+1 redundancy)
- SAS Backplanes for 4x or 8x 2.5" HDD
- with cable connection to on-board or modular RAID Controller

Drives / Bavs

- 4x 2.5" SAS / SATA HDD or 8x 2.5" SAS / SATA HDD option
- 1 bay SATA DVD-ROM 0,5" height (option if 4x 2.5" HDD only)
- Integrated ServerView Diagnostics Technology (Diagnosis LED's) for indication of internal failed components

Systemboard D3302 with:

* Up to two Xeon DP CPU's (Socket-R)

with 2 serial QPI links (Quick Path Interconnect) and four memory channels per CPU First CPU has to be selected for an orderable basic unit,

- * Chipset Intel® C600 Series (codenamed Patsburg)
- * 4 PCle slots
 - -2x PCIe-3 x8 (Low Profile cards)
 - -1x PCIe-3 x16 (Low Profile cards)
 - -1x PCIe-3 x8 internal for modular RAID controller only
- * 24 memory slots for max. 1.536GB RAM DDR3 available
- Memory is divided into 12 DIMMs per CPU (4 channels with 3 slots per channel)

Possible max. configurations are:

24x 64GB LRDIMM (eight rank modules) = 1536GB

16x 16GB RDIMM quad rank modules) = 384GB

16x 8GB UDIMM (dual rank modules) = 128GB (on special Release only)

First Memory (one module) has to be selected for an orderable basic unit per CPU

- Memory upgrade is possible module wise
- Memory mirrroring is supported with 2 identical modules in channel A+B/C+D CPU 1 or E+F/'G+H CPU 2
- Rank sparing mode is supported with min. 2x 1R/2R or 1x 4R modules for RDIMM or LRDIMM
- SDDC (Chipkill) is supported for RDIMMs (except x8 organisation) and LRDIMMs,
- Dual Port 10/100/1000 x4 PCI Express* Gigabit Ethernet Intel LAN controller Powerville on-board
- * iRMC S4 (integrated Remote Management Controller) on-board server management controller with dedicated 10/100/1000 Service LAN-port and integrated graphics controller.

The Service LAN-port can be switched alternatively on standard Gbit LAN port 1

Graphics Controller integrated in iRMC S4 (integrated Remote Management Controller): 1600x1200x16bpp 60Hz, 1280x1024x16bpp 60Hz, 1024x768x32bpp 75Hz, 800x600x32bpp 85Hz, 640x480x32bpp 85Hz

(1280x1024x24bpp 60Hz only possible if local monitor or remote video redirection is off)

Α

Interfaces at the rear:

- * 1x VGA (15 pins)
- * 3x USB 2.0 (UHCI) with 480MBit/s, no USB wakeup
- * 2x LAN RJ45, 1x Service-LAN RJ45

Interfaces on the front:

- * 2x USB 2.0 (UHCI) with 480MBit/s, no USB wakeup
- * 1x VGA (15 pins) as an option
- * 1x Service-LAN RJ45 as an option

Interfaces internal:

- * 1x USB 2.0 (UHCI) with 480MBit/s for dongle funcionality (uSSD memory), no USB wakeup
- * 1x SATA interface for DVD (only usable with 4x 2.5" HDD baseunit + DVD Option)
- * 4x SATA/SAS interface for 4 SATA/SAS HD's (only usable for 4x 2.5" HDD baseunit)
- * 2x USB 2.0 ports for internal USB redirection connected to BMC

Software

- ServerView Suite Software package incl. ServerStart, ServerBooks, Management Software and Updates
- Documentation engl. (multilingual on CD)



Note: Rack Mounting kit and Power Cord for RX200S8 is not included in the basic unit and has to be configured separately

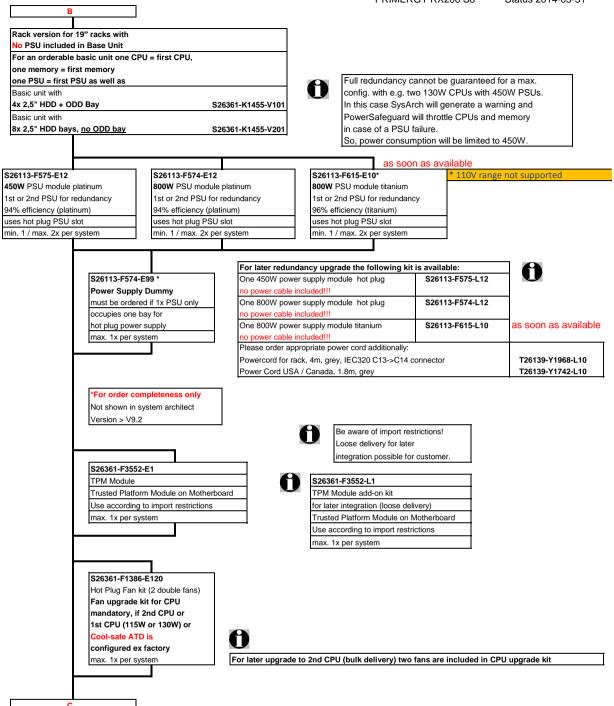


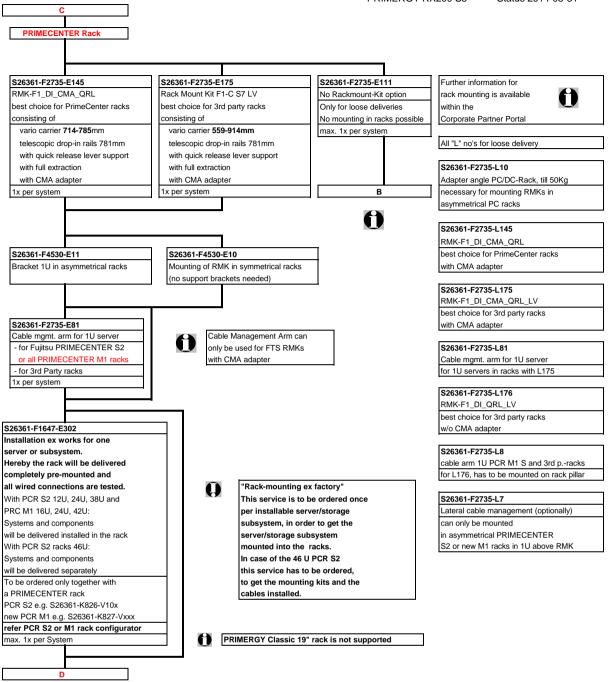
Cables included in basic unit

Connections	Cable	PRIMERGY RX200 S8	Key:
1. SATA DVD	0	O (optional)	⊚ SAS ⊝ SATA
2. 4-port SAS cable HDDs	0	<u> </u>	
3. 4-port SAS cable HDDs	0	⊚ (optional)	

Conditions for SATA cable and one ore two 4-port SAS cables see description "Cables" above

В







There are 2 processor sockets available.

The first socket is always equipped with the **first CPU** which can be selected via configurator

It is also possible to upgrade a dual-processor system later on with a second CPU Two processors with different type are not possible

If 1CPU with a TDP >= 115W is used, the hot plug redundant fan kit (S26361-F1386-E120) is required.

If 2CPUs are used, the hot plug redundant fan kit (\$26361-F1386-E120) is required.

If Cool-safe Advanced Thermal Design is used, the hot plug redundant fan kit (S26361-F1386-E120) is required.

A multi-processor operating system is required for a dual-processor system.

Max. two CPU's can be selected per basic unit						
One of following CPU's has to be selected as first CPU						
for an orderable basic unit						
Optional second CPU has to be the same type like the first CPU						
Basic 4C CPU's						
- 1x 64-bit Intel Xeon (10MB Smart Cache)						
1333 MHz DDR3 Bus; 6,40 GT/s QPI Bus and passive heat sink						
occupies socket for one CPU						
Xeon E5-2603v2 4C/4T 1.80GHz 10MB 6.40GT/s 1333MHz 80W	S26361-F3800-E180					
Xeon E5-2609v2 4C/4T 2.50GHz 10MB 6.40GT/s 1333MHz 80W	S26361-F3800-E250					
Standard Turbo 6C/8C CPU's						
- 1x 64-bit Intel Xeon (15/20MB Smart Cache); Hyper-Threading (HT);						
1600 MHz DDR3 Bus; 7,20 GT/s QPI Bus and passive heat sink						
occupies socket for one CPU						
Xeon E5-2620v2 6C/12T 2.10GHz 15MB 7.20GT/s 1600MHz 80W	S26361-F3801-E210					
Xeon E5-2630v2 6C/12T 2.60GHz 15MB 7.20GT/s 1600MHz 80W	S26361-F3801-E260					
Xeon E5-2640v2 8C/16T 2.00GHz 20MB 7.20GT/s 1600MHz 95W	S26361-F3801-E200					
Advanced Turbo+ 8C/10C CPU's						
- 1x 64-bit Intel Xeon (20/25MB Smart Cache); Hyper-Threading (HT);						
1866 MHz DDR3 Bus; 8,00 GT/s QPI Bus and passive heat sink						
occupies socket for one CPU						
Xeon E5-2650v2 8C/16T 2.60GHz 20MB 8.00GT/s 1866MHz 95W	S26361-F3802-E260					
Xeon E5-2660v2 10C/20T 2.20GHz 25MB 8.00GT/s 1866MHz 95W	S26361-F3802-E220					
Xeon E5-2670v2 10C/20T 2.50GHz 25MB 8.00GT/s 1866MHz 115W	S26361-F3802-E250					
Xeon E5-2680v2 10C/20T 2.80GHz 25MB 8.00GT/s 1866MHz 115W	S26361-F3802-E280					
Xeon E5-2690v2 10C/20T 3.00GHz 25MB 8.00GT/s 1866MHz 130W	S26361-F3802-E300					
Segment Optimized CPU's						
- 1x 64-bit Intel Xeon (15/25/30MB Smart Cache); Hyper-Threading (HT);						
1866 MHz DDR3 Bus; 8,00 GT/s QPI Bus and passive heat sink						
occupies socket for one CPU						
Xeon E5-2637v2 4C/8T 3.50GHz 15MB 8.00GT/s 1866MHz 130W	S26361-F3803-E350					
Xeon E5-2643v2 6C/12T 3.50GHz 25MB 8.00GT/s 1866MHz 130W	S26361-F3803-E330					
Xeon E5-2667v2 8C/16T 3.30GHz 25MB 8.00GT/s 1866MHz 130W	S26361-F3803-E300					
Xeon E5-2695v2 12C/24T 2.40GHz 30MB 8.00GT/s 1866MHz 115W \$26361-F3803-						
Xeon E5-2697v2 12C/24T 2.70GHz 30MB 8.00GT/s 1866MHz 130W	S26361-F3803-E270					
Low Power 6C/10C CPU's						
- 1x 64-bit Intel Xeon (15/25MB Smart Cache); Hyper-Threading (HT);						
1600 MHz DDR3 Bus; 7,20/8,00 GT/s QPI Bus and passive heat sink						
occupies socket for one CPU						
Xeon E5-2630Lv2 6C/12T 2.40GHz 15MB 7.20GT/s 1600MHz 60W	S26361-F3804-E240					
Xeon E5-2650Lv2 10C/20T 1.70GHz 25MB 8.00GT/s 1600MHz 70W	S26361-F3804-E170					



Max. DDR3 Bus Speed depends on:

- max. DDR3 Bus Speed from the CPU and
- max. DDR3 Memory Speed and
- max. memory modules on one memory channel For CPUs which do not offer 1866 MHz support, (Basic, Standard & Low Power class), System Architect will not offer memory modules

supporting this frequency.

E

Section III Memory



- There are 12 memory slots per CPU for max.

768GB LRDIMM (12x 64GB 8R) 192GB RDIMM (12x 16GB 2R)

64GB UDIMM (8x 8GB) on special Release only

=> max. 1.536GB for two CPU's (768GB per CPU), using LRDIMM

- The memory area is divided into 4 channels per CPU with 3 slots per channel
- Slot 1 of each channel belongs to memory bank 1, the slot 2 belongs to memory bank 2, slot 3 belongs to memory bank 3

Registered, LR DIMMs and unbuffered memory modules can be selected

No mix of registered, load reduced and unbuffered modules allowed.

Memory can be operated at 1.5V or 1.35V, even if the modules are of low voltage type.

Memory operating voltage can be set within BIOS (1.5V is default setting for max. speed).

In a single DIMM per channel configuration, following frequencies are supported:

- 1.5V 1866MHz max (depending on CPU)
- 1.35V 1600MHz max (depending on CPU, up to two LRDIMM per channel)
- 1.35V 1333MHz max (up to two UDIMM or RDIMM per channel)

In a 3 DIMMs per channel configuration, memory will operate at 1.35V or 1.5V (no UDIMM allowed).

SDDC (Chipkill) is supported for registered / load reduceed x4 organized memory modules only

1.) In the "Independent Channel Mode" is following configuration possible

Channels can be populated in any order in Independent Channel Mode. All four channels may be populated in any order and have no matching requirements. All channels must run at the same interface frequency but individual channels may run at different DIMM timings (RAS latency, CAS latency, and so forth)

No mix of registered, load reduced and unbuffered modules allowed.

2.) "Rank Sparing Mode" configuration

- Within a memory channel, one rank is a spare of the other ranks.

The Spare Rank is held in reserve and is not available as system memory

For the effective memory capacity, please refer to the spreadsheet below.

The BIOS is set to the rank sparing setting.

Minimum configuration is: 2x 1R, 2x 2R or 1x4R DDR3 module per channel

This mode is not supported by unbuffered memory modules

3.) "Performance Mode" configuration

- In this configuration, the memory module population ex factory is spread across all channels.

The BIOS is set to the max. performance for memory.

Minimum configuration is: 4x identical modules per CPU

4.) In the "Mirrored Channel Mode" is following configuration possible

- Each memory bank can optionally be equipped with 4x registered or load reduced or unbuffered DDR3 modules

In each memory bank channel A and B / C and D of CPU 1 or channel E and F / G and H of CPU 2 have to be equipped with identical modules for mirrored channel mode.

In channel B / D is always the mirrored memory of channel A / B of CPU 1

In channel F / H is always the mirrored memory of channel E / G of CPU 2 $\,$

Minimum configuration is: 4x identical modules per CPU

This mode is not supported by unbuffered memory modules

S26361-F3694-E10 Independent Mode

Independent Channel Mode allows all channels to be populated in any order. No specific Memory RAS features are defined

Requires min 1 memory Module per CPU

S26361-F3694-E1 Rank Sparing Mode Installation

BIOS Setup factory preinstalled to this mode. One Rank is spare of other ranks on the same channel. Spare Rank is not shown in System Memory. For effective capacity within a channel, please have a look below.

Supported for RDIMM / LRDIMM only.

Requires min 2x 1R/2R or 1x 4R modules per CPU

S26361-F3694-E2 Performance Mode Installation

BIOS Setup factory preinstalled for max. Performance, LV memory might be set to 1.5V operation. Four identical memory modules

will be equipped in one memory bank to achieve highest memory performance. All four modules are active and full capacity can be used.

Multiple of 4 identical modules to be configured per CPU

S26361-F3694-E3 Mirrored Channel Mode Installation

BIOS Setup factory preinstalled to this mode. Four identical memory modules are always equipped in one memory bank to use the

Mirrored channel Mode. Only two modules contain active data, the remain two modules contain mirrored data

Supported for RDIMM / LRDIMM only.

Multiple of 4 identical modules to be configured per CPU

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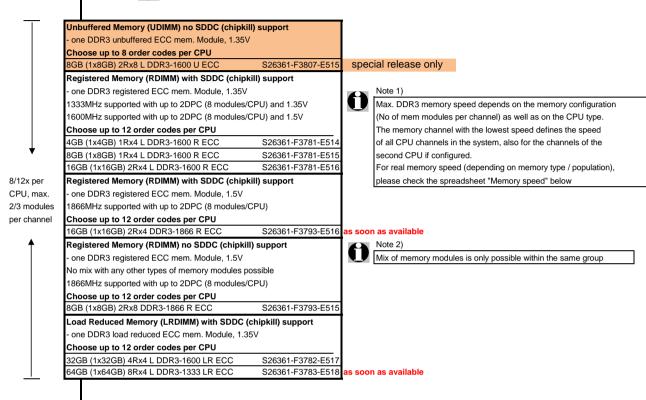
1x per CPU



Effective Memory capacity / Rank Sparing Mode, 1 Channel populated									
		RDI	MM	LRD					
	4GB 1R	8GB 1R	8GB 2R	16GB 2R	32GB 4R	64GB 8R			
1DPC	na	na	na	na	24GB	48GB			
2DPC	4GB	8GB	12GB	28GB	56GB	112GB			
3DPC	8GB	16GB	20GB	44GB	80GB	160GB			



Minimum one memory module or order code per CPU = first memory



Memory Configuration PRIMERGY RX200 S8

Each CPU offers 12 Slots for DDR3 Memory Modules organised in 3 Banks and 4 Channels.

If you need more than 12 Slots you have to configure the 2nd CPU.

Depending on the amount of memory configured you can decide between 4 basic modes of operation (see explanation below).

There are 3 different kinds of DDR3 Memory Modules available: UDIMM / RDIMM and LRDIMM UDIMM / RDIMM / LRDIMM offer different functionality. Mix of UDIMM / RDIMM / LRDIMM is not alloved.

If 1.5V and 1.35V DIMMs are mixed, the DIMMs will run at 1.5V

Mode	Configuration	UDIMM	RDIMM	RDIMM	Application					
		ODIIVIIVI	KDIIVIIVI	LRDIMM						
		х8	х8	x4						
SDDC (chipkill) support	any	no	no	yes	detect multi-bit errors					
Independant Channel Mode	1, 2 or 3 Modules per Bank	yes	yes	yes	offers max. flexibility, upgradeability, capacity use UDIMM modules for lowest cost					
Mirrored Channel Mode *)	4 identical Modules / Bank	no	no	yes	offers maximum security					
Performance Mode	4 identical Modules / Bank	yes	yes	yes	offers maximum performance and capacity					
Rank Sparing Mode *)	min. 2 Ranks / Channel	no	no	yes	balances security and capacity					

^{*)} For the delivery ex works the system will be prepared with dedicated BIOS setting.

Capacity	Configuration	UDIMM	RDIMM	LRDIMM	Notes
Min. Memory per CPU	1 Module / CPU	1x4GB	1x4GB	1x32GB	with one CPU
Max. Memory per CPU	8/12 Modules / CPU	8x4GB	12x16GB	12x64GB	with one CPU
Max. Memory per System	16/24 Modules / System	64GB	384GB	1536GB	if second CPU is configured

Memory-Speed:

Max. DDR3 memory speed depends on the memory configuration on one memory channel and the speed of the CPU The memory channel with the lowest speed defines the speed of all CPU channels in the system

Mem. Speed provided by CPU	Real maximum memory-bus speed depending on CPU type, memory configuration (DPC) and voltage setting (BIOS)																	
	UDIMM 1866MHz				RDIMM 1866MHz						LRDIMM 4R 1866MHz							
Voltage setting (BIOS)	1.5\	/ [defa	ault]		1.35V			1.5V [default] 1.35V			1.5V [default]			1.35V				
	1	2	3	1	2	3	1	2	3	1	2	3	1	2	3	1	2	3
	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC
CPU with 1866MHz DDR3 Bus	1866	1600	-	1333	1333	-	1866	1866	1066	1333	1333	800	1866	1600	1066	1600	1600	1066
CPU with 1600MHz DDR3 Bus	1600	1600	-	1333	1333	-	1600	1600	1066	1333	1333	800	1600	1600	1066	1600	1600	1066
CPU with 1333MHz DDR3 Bus	1333	1333	-	1333	1333	-	1333	1333	1066	1333	1333	800	1333	1333	1066	1333	1333	1066

1R - Single Rank 4R - Quad Rank 2R - Dual Rank 8R - Eight Rank

1DPC = 1 DIMM per Channel 2DPC = 2 DIMM per Channel 3DPC = 3 DIMM per Channel

Configuration hints:

- The memory sockets on the systemboard offer a color coding:

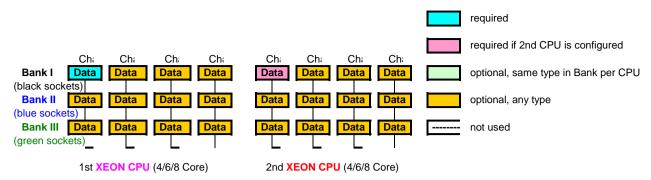
Bank II black sockets
Bank III blue sockets
Bank III green sockets

- A so called Bank consits of 1 memory module on every Channel available on one CPU (examples see below)

Bank I on CPU 1/2 up to 4 memory modules connected to Channel A - H on the 1st/2nd CPU up to 4 memory modules connected to Channel A - E on the 1st/2nd CPU up to 4 memory modules connected to Channel A - E on the 1st/2nd CPU up to 4 memory modules connected to Channel A - E on the 1st/2nd CPU (can not be populated by UDIMM or 4R RDIMM memory modules)

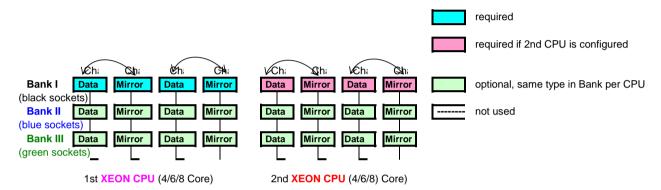
- See below and next page for a detailed descriptions of the memory configuration supported.

1. Independent Channel Mode



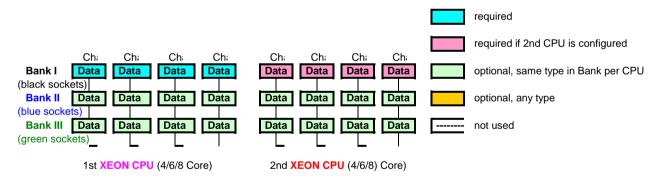
Independent Channel Mode allows all channels to be populated in any order Can run with differently rated DIMMs and use the settings of the slowest DIMM installed in the system

2. Mirrored Channel Mode



Mirrored Channel Mode requires identical modules on channel A,B, C, D (1st CPU) or channel E, F, G and H (2nd CPU) 50% of the capacity is used for the mirror => the available memory for applications is only half of the installed memory If this mode is used, a multiple of 4 identical modules has to be ordered.

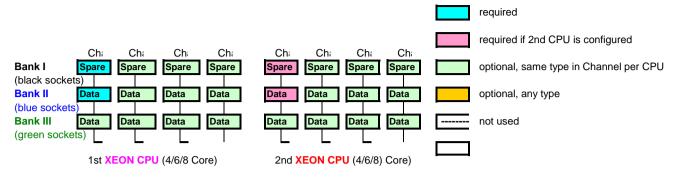
3. Performance Channel Mode



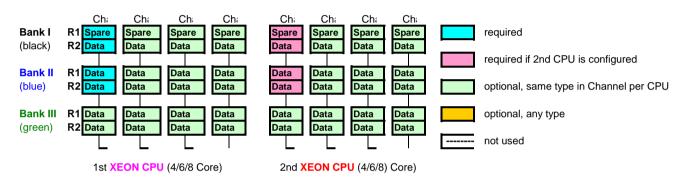
Performance Channel Mode requires identical modules on all channels of each Bank per CPU. If this mode is used, a multiple of 4 identical modules has to be ordered.

4. Rank Sparing Mode

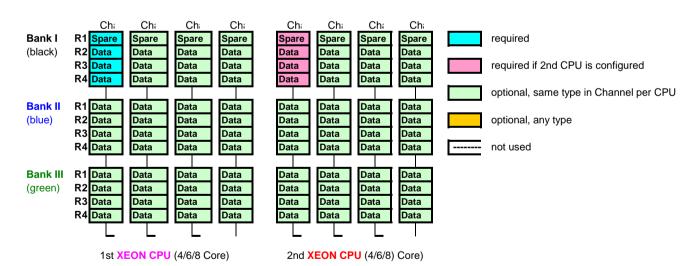
1-Rank Memory modules (RDIMM)



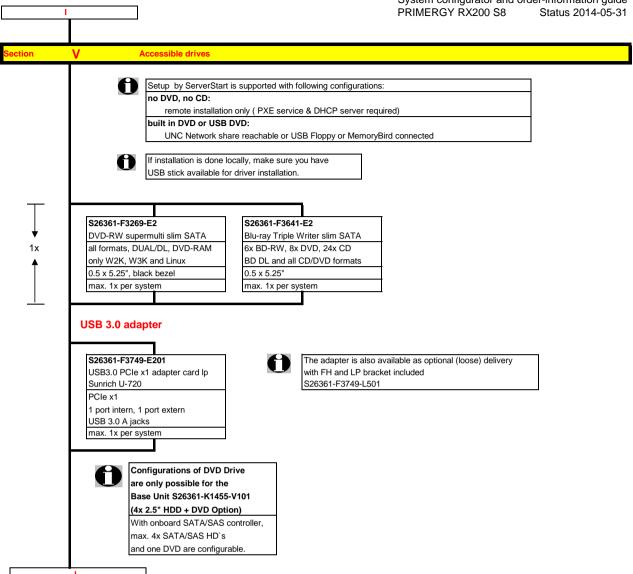
2-Rank Memory modules (RDIMM)

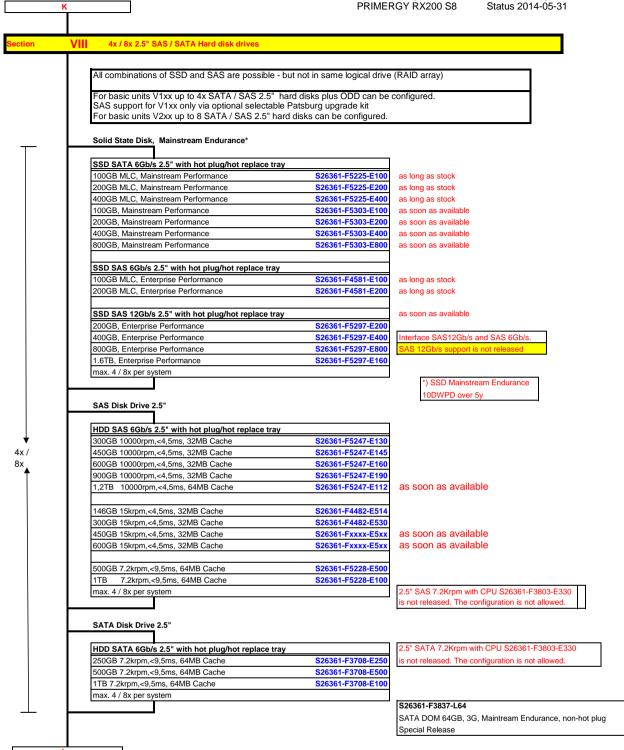


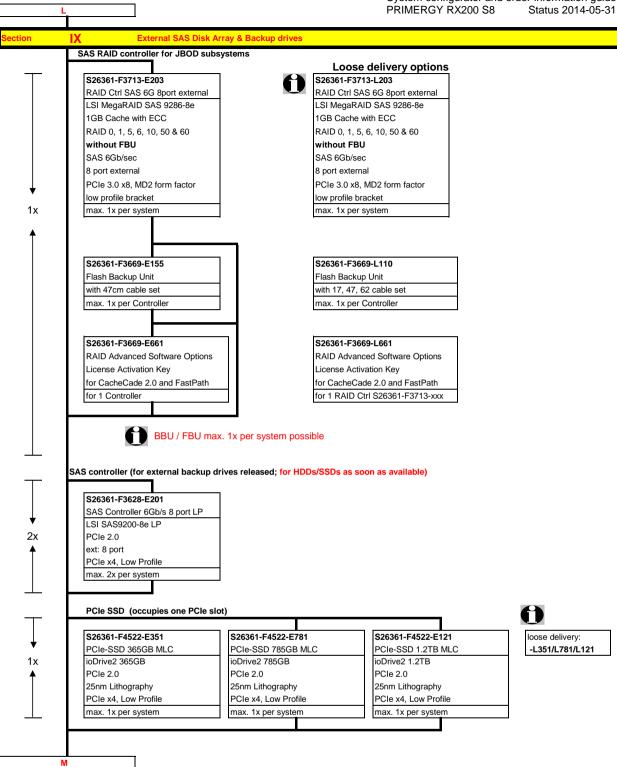
4-Rank Memory modules (LRDIMM)

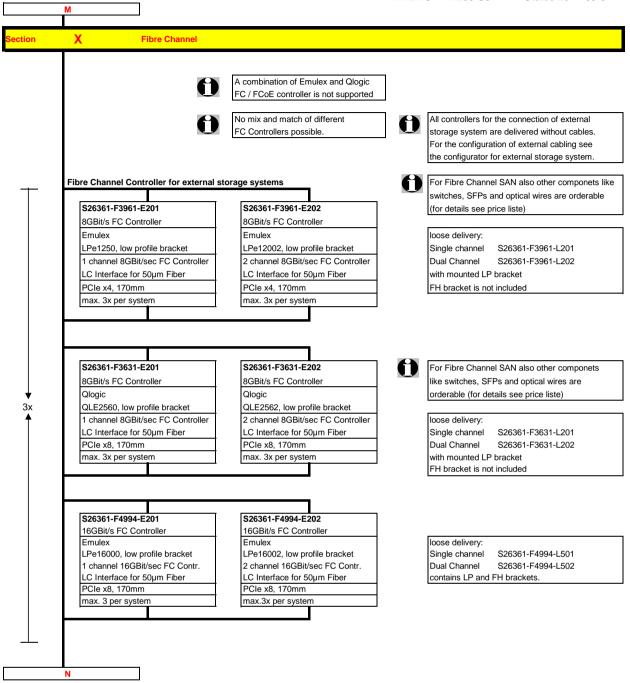


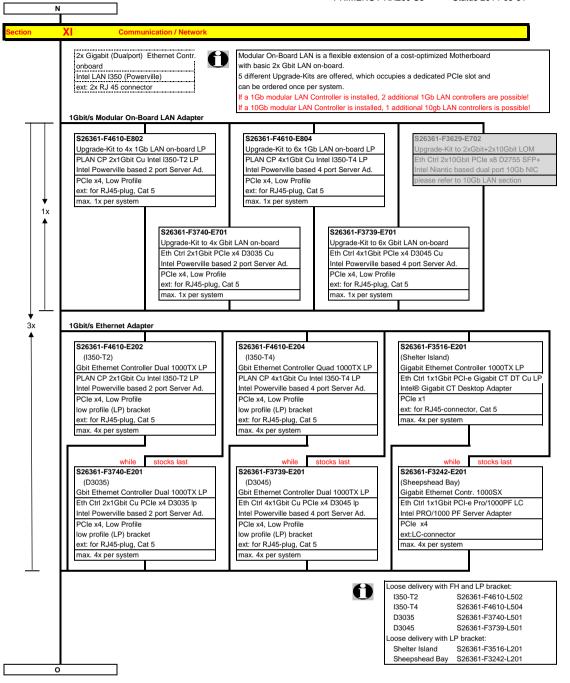
Rank Sparing Mode requires identical modules (same capacity and technology) within the same channel. The available memory for applications will vary depending on configuration. Please refer to the spreadsheet above "Effective Memory capacity with active Rank Sparing Mode". Population rule for Rank sparing mode is to achieve max. available memory, e.g. 6 DIMMs will be spread across two channels, each with 3DPC

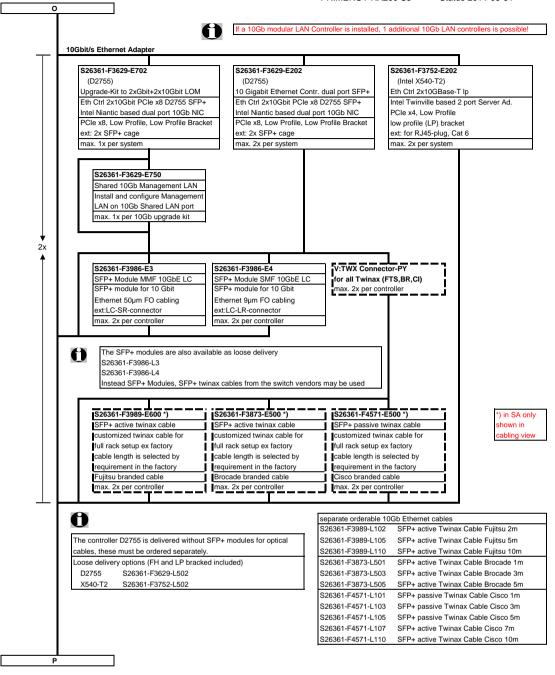


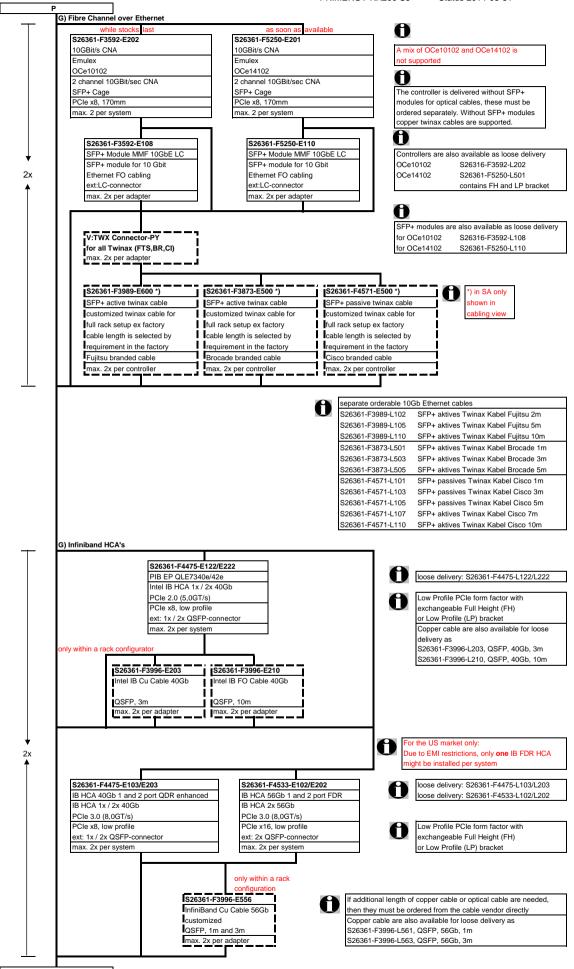


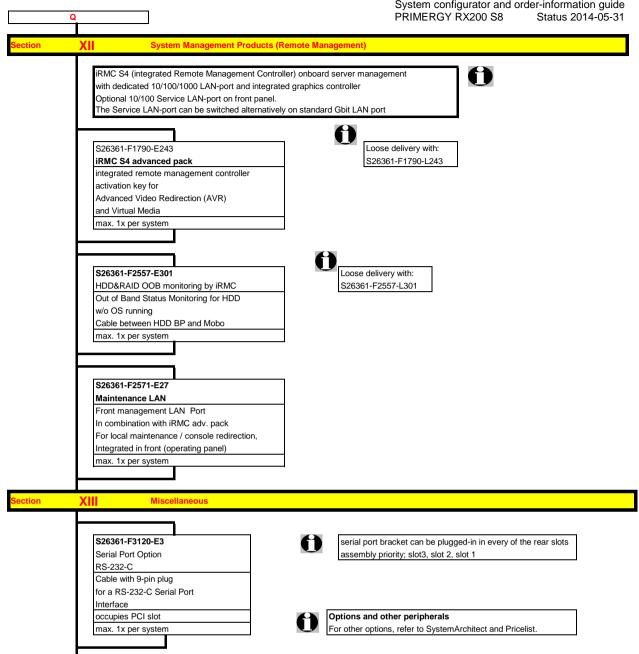




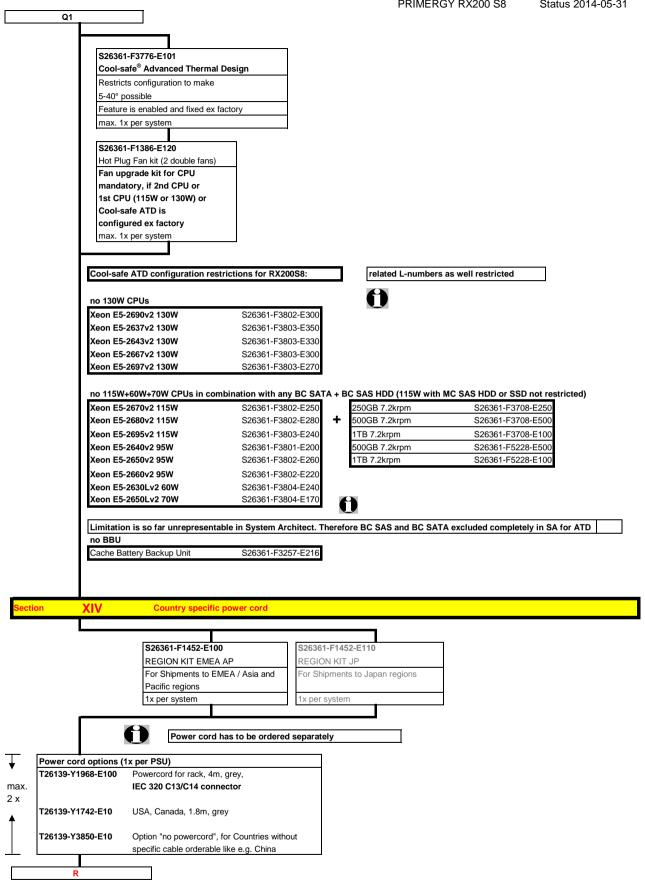


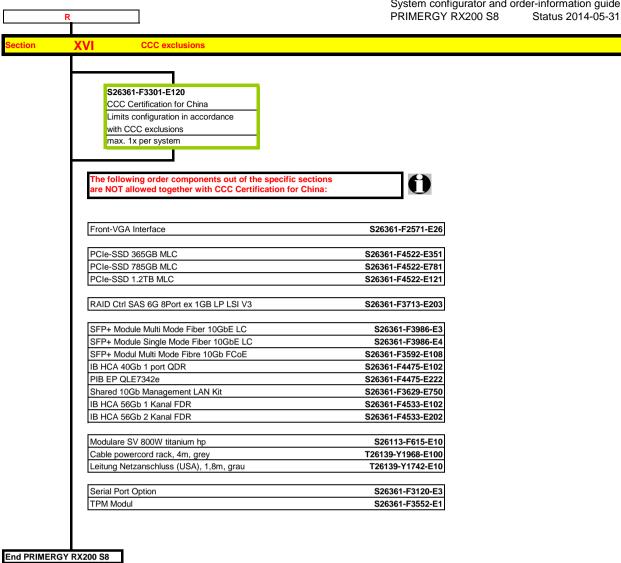






Q1





Change Report

Date	Order number	Changes
Dute	Graci Hamber	- Traing 00
2014-06-05	S26361-F5250-L201	new CNA OCe14102 added
2014-03-17	S26361-F3739-E201	phase out
2014-03-17	S26361-F3740-E201	phase out
2014-03-17	S26361-F3610-E202	EOL
2014-03-17	S26361-F4475-E102/L102	"IB HCA 40Gb 1 port QDR" Removed.
2014-02-25	320301-1 4473-E 102/E102	comment "SSD/SAS requires RAID Controller" removed; typo!
2014-02-23	S26361-F5303-*	New SATA SSDs added.
2014-01-30	S26361-F5297-*	New SAS 12G SSDs added.
2014-01-30	S26361-F3554-E8	restricted for ATD
2013-12-10	S26361-F3837-L64	SATA DOM added
2013-11-29	S26361-F3301-E120	Restrictions CCC Certification for China updated
2013-11-27	320301-F3301-E120	restrictions for ATD adjusted; 95W as well restricted in combination with BC
		SSD support with On-Board controller.
2013-10-28 2013-10-28		restriction for 2.5" BC-SAS HDD with "*F3554-E8" removed.
	optional USB Comps	
2013-10-18	optional USB Comps	no longer available
2013-10-16		restrictions for Cool-safe ATD changed
2013-10-14		restrictions for Cool-safe ATD changed
2013-09-30		restrictions for Cool-safe ATD added
2013-09-30		CCC restrictions added
2013-09-30		Restriction for HDDs 2.5" 7.2Krpm HDD with CPU E5-2643v2
2013-09-19		Memory hint on CPU page extended
2013-09-13	S26361-F5247-E112	HDD 2.5" 1.2TB SAS 10K added.
2013-09-12		First Release
<u> </u>		